

Revision Record

| Revision | DCO | Description | Engineering Approval | Date | QA Approval | Date | Release Date |
|----------|------|--|----------------------|--|-------------|----------|--------------|
| - | | Initial Release | KS | 2/4/97 | JB | 2/4/97 | 2/4/97 |
| A | 328 | Revise per DCO 328 | KS | 3/4/98 | JB | 3/4/98 | 3/4/98 |
| B | | Correct typos on par. 4.6.3 and Table 1 | RE | 2/7/02 | MD | 2/5/02 | 2/7/02 |
| C | | Add paragraphs 4.2.4 and 4.2.12 | RE | 4/24/02 | MD | 4/24/02 | 4/24/02 |
| D | | Corrections to Table IV | RE | 11/13/02 | MD | 11/13/02 | 11/13/02 |
| E | | Update par. 4.2.6; change references from MIL-O-55310 to MIL-PRF-55310 MIL-S-19500 to MIL-PRF-19500 Corrected Table 1 | EJ | 10/30/07 | CA | 10/30/07 | 10/30/07 |
| F | | Updated par. 4.2.13, and Table I; New verbiage reflect standard practice and verbiage as noted in MIL-PRF(O)-55310 | CH MD | 5/19/09 5/19/09 | CA | 5/20/09 | 5/21/09 |
| G | 2358 | Add Note 3/ to Table VII. Clarified par. 3.4.4 Correct Tables I, II, and IV Add Note 4 to Table V | RD CH MD JA | 11/19/13 11/19/13 11/19/13 11/20/13 | CP | 11/19/13 | 11/21/13 |
| H | 3694 | 2.1 Add Ref to F1221 3.4.8.1 add "free" 3.4.8.2 "5oz" Expand non-flight par/ 3.4.14 Tables I and V Leak methods Tables III and VII add new parameters | RD | 4/30/15 | CP | 4/30/15 | 4/30/15 |
| J | 6569 | Migrate document to new format. Update par 3.4.3. Update par 3.4.14. to refer to F1221 Table IV, Note 7, updated ESDS Class | CH JA RD | 3/23/17 3/24/17 3/27/17 | DM | 3/25/17 | 3/9/18 |



UNLESS OTHERWISE SPECIFIED
Dimensions are in Inches

| Tolerances | | |
|-------------|--------------------------------|-----------------------|
| Decimal | Fraction | Angular |
| .xxx ± .005 | | |
| .xx ± .02 | $\frac{x}{x} \pm \frac{1}{16}$ | $x^\circ \pm 2^\circ$ |
| .x ± .1 | | |

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GENERAL PRODUCT SPECIFICATION CONTROL DRAWING

| Initial Release | | Q-Tech Corporation 10150 West Jefferson Boulevard Culver City, CA 90232-3510 USA | | | |
|----------------------------|--------|---|----------|--------------|----------------|
| Prepared | Date | | | | |
| Kelly Stanford | 2/4/97 | TITLE | | | |
| Checked | Date | HYBRID CRYSTAL OSCILLATOR, CLASS S, GENERAL SPECIFICATION FOR | | | |
| Trisha Villegas | 2/4/97 | | | | |
| Engineering Approval | Date | DRAWING NO. | | REVISION | |
| Kelly Stanford | 2/4/97 | 0401-00298-0001 | | J | |
| Quality Assurance Approval | Date | SCALE | SIZE | CAGE CODE | PAGE |
| Jack Beck | 2/4/97 | NONE | A | 51774 | 1 of 12 |
| Released | Date | | | | |
| Maritza Galdamiz | 2/4/97 | | | | |

1 SCOPE

- 1.1 Scope. This specification establishes the general quality and reliability requirements for a family of hybrid, hermetically sealed, crystal oscillators for use in space flight missions. Oscillators shall be produced by a manufacturer presently listed on the MIL-PRF-55310 QPL (Qualified Products List).
- 1.2 Part number. The part number shall be as specified in the detail specification.

2 APPLICABLE DOCUMENTS

- 2.1 Specifications and Standards. Unless otherwise specified, the following documents shall be applicable to this specification to the extent specified herein.

SPECIFICATIONS

MILITARY

MIL-PRF-19500 Semiconductor Devices, General Specification For
MIL-PRF-55310, Crystal Oscillators, General Specification For
MIL-PRF-38535, Integrated Circuits, (Microcircuits) Manufacturing, General Specification For
MIL-PRF-38534, Hybrid Microcircuits, General Specification For

Q-TECH

F1221, Definitions for Hybrid Product Development Levels

STANDARDS

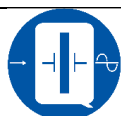
MILITARY

MIL-STD-202, Test Methods for Electronic and Electrical Component Parts
MIL-STD-883, Test Methods and Procedures for Microelectronics
MIL-STD-975, NASA Standard Electrical, Electronic, and Electromechanical (EEE) Parts List

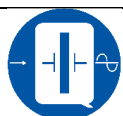
- 2.2 Conflicting requirements. In the event of conflict between requirements of this specification and other requirements of the applicable detail drawing, the precedence in which requirements shall govern, in descending order, is as follows:
 - a) Applicable Customer purchase order.
 - b) Applicable Customer detail drawing.
 - c) This specification.
 - d) Other specifications or standards referenced in 2.1 herein.
- 2.3 Customer purchase order special requirements. Additional special requirements shall be specified in the applicable Customer purchase order when additional requirements or modifications specified herein are needed for compliance to special program or product line requirements

3 REQUIREMENTS

- 3.1 Item Requirements. The individual item requirements shall be as specified herein and the detail specification.



- 3.2 Case Outline. The case outline and terminal connections shall be as specified in the detail specification.
- 3.2.1. Maximum Ratings. Unless otherwise specified, the maximum ratings shall as specified in the detail specification.
- 3.3 Electrical Performance Requirements. The electrical performance requirements shall be as specified herein and the applicable detail specification.
- 3.4 Design and Construction. The design and construction of the crystal oscillator shall be as specified herein. As a minimum, the oscillators shall meet the design and construction requirements of MIL-PRF-55310.
- 3.4.1. Radiation Hardness. No elements shall be used in the unit that latch-up in a single event upset (SEU) environment. All devices used in the unit shall be capable of meeting all electrical performance requirements after being subjected to the total dose level specified in the detail specification.
- 3.4.2. Element derating. All active and passive elements shall be derated in accordance with the applicable hybrid microcircuit element requirements of MIL-STD-975. Elements shall not operate in excess of derated values.
- 3.4.3. Element evaluation. All piece parts shall be derived from lots that meet the element evaluation requirements of MIL-PRF-38534, Class K.
- 3.4.4. Quartz crystal material. Unless otherwise specified by the detail specification, the quartz crystal material shall be swept synthetic, grade 2.2 million or better.
- 3.4.5. Crystal Mounting. The crystal element shall be three-point minimum mounted in such a manner as to assure adequate crystal performance when the oscillator is subjected to the environmental conditions specified herein.
- 3.4.6. Thick Film Hybrid Technology. When possible, all piece part electronic elements (except the quartz crystal resonator) shall be mounted on the surface of thick film substrates. All lead attachment shall have appropriate strain relief. There shall be no solder allowed internally.
- 3.4.7. Package material and finish. The package material and finish shall be in accordance with MIL-PRF-38534 and as specified in the detail specification.
- 3.4.8. Lead material and finish. The lead material and finish shall be in accordance with MIL-PRF-38534 and as specified in the detail specification.
- 3.4.8.1 Maximum allowable leak rate. The maximum allowable leakage rate shall be as specified by MIL-STD-883, method 1014 based on the internal free cavity volume. The hermetic seal (fine and gross leak) tests shall be in accordance with MIL-STD-883, Method 1014.
- 3.4.8.2 Weight. The weight of the crystal oscillator shall be 5 ounces maximum.
- 3.4.9. Electrical performance limits and conditions. Unless otherwise specified, the electrical performance limits and conditions shall be as specified in the detail specification.
- 3.4.9.1 Spurious Output Frequencies. The oscillator shall not break into other (unwanted) modes of oscillations.
- 3.4.10. Delta Criteria. The crystal oscillator shall meet the parameter delta criteria of Table II herein. The change in the parameter (delta) shall be calculated between the initial measurement and the present (interim or final) measurement.
- 3.4.11. Marking. Each unit shall be permanently marked with the manufacturer's name or symbol, part



number, lot date code number, and serial number. The unit shall be marked with the outline of an equilateral triangle near pin 1 to show that it contains devices which are sensitive to electrostatic discharge.

3.4.12. Traceability. Material, element and process traceability requirements shall be as specified by MIL-PRF-38534 for class K hybrids.

3.4.13. Rework provisions. Rework shall be in accordance with the provisions of MIL-PRF-38534 except rebonding to microcircuit elements shall be as specified by MIL-PRF-38535 and transistor elements shall be as specified by MIL-PRF-19500.

3.4.14. Non-flight oscillators. Unless otherwise specified in the detail specification, the general requirements for non-flight hardware (Breadboard (B), Engineering (E), and Engineering Qualification (EQ) Models) shall be defined in F1221, Definitions for Hybrid Product Development Levels.

4 QUALITY ASSURANCE PROVISIONS

4.1 Responsibility for Inspection. Unless otherwise specified in the contract or purchase order, the supplier shall be responsible for the performance of all inspection requirements as specified. Except as otherwise specified in the contract or purchase order, the supplier may use their own or any other facilities suitable for the performance of the inspection requirements specified herein, unless disapproved by Customer. Customer reserves the right to perform any of the inspections set forth in the specification where such inspections are deemed necessary to assure supplies and services conform to prescribed requirements, and to return any product failing to meet the specified requirements.

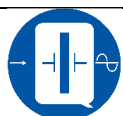
4.2 Screening. Hybrid crystal oscillators shall have been subjected to and successfully passed all the screening tests as specified in table I herein in order to be acceptable for delivery. All variables data shall be read and record. Devices which fail any test criteria in the screening sequence shall be removed from the lot at the time of observation or immediately at the conclusion of the test in which the failure was observed. Once rejected and verified as a device failure, rework and subsequent rescreening in accordance with the rework provisions of may be performed. Devices which fail during screening may be used for Group B inspection provided that they have completed screening through completion of the burn-in testing.

4.2.1. Nondestructive bondpull. Except for the wires connecting the crystal to the circuit (if available), 100 percent nondestructive bond pull, shall be performed on each hybrid crystal oscillator in accordance with MIL-STD-883, method 2023. The total number of failed wires and the total number of devices failed shall be recorded. The lot shall have a percent defective allowable (PDA) of 2 percent or less based on the total number of wires pulled in the production lot.

4.2.2. Internal visual inspection. Internal visual inspection shall be in accordance with the condition K (class S) requirements of MIL-STD-883, methods 2017 and 2032. During the time interval between final internal visual inspection and preparation for sealing, hybrid crystal oscillators shall be stored in a dry, controlled environment as defined in MIL-STD-883, method 2017 or in a vacuum bake oven. The following details shall apply:

- a) The final internal visual inspection shall occur after crystal resonator installation and prior to cover seal. Hybrid crystal oscillator inspection and preparation for sealing shall be in a class 100,000 environment as defined in Federal Standard 209. Hybrid crystal oscillators shall be in a covered container when transferred from one controlled environment to another.

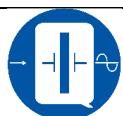
4.2.3. Stabilization bake. Stabilization bake shall be performed prior to package seal. Stabilization bake shall be performed in a vacuum environment.



- 4.2.4. Temperature cycling. Unless otherwise specified, temperature cycling shall be in accordance with Table I herein.
- 4.2.5. Constant acceleration. Constant acceleration shall be performed in the Y1 orientation.
- 4.2.6. Particle impact noise detection (PIND) test. PIND testing shall be performed in accordance with MIL-STD-883, method 2020, condition B. The PIND test shall be performed using five independent passes and all failures found at the end of each pass are rejected. The survivors of the last pass are acceptable. The cumulative number of defective devices shall not exceed 25 percent.
- 4.2.7. Pre burn-in electrical characteristics test. Unless otherwise specified, pre burn-in electrical testing shall consist of the tests listed in Table VII. Electrical performance limits shall be in accordance with the detail specification.
- 4.2.8. Burn-in. The burn-in period shall be 320 hours minimum. The 320 hour burn-in period shall be divided into two successive 160 hour minimum burn-in periods. Electrical testing shall be performed after the first burn-in to select acceptable devices for the second burn-in.
- 4.2.9. Interim electrical testing. Unless otherwise specified, interim electrical testing shall consist of the tests listed in Table VII. Electrical performance limits shall be in accordance with the detail specification.
- 4.2.10. Final electrical testing. Unless otherwise specified, final electrical testing shall consist of the tests listed in Table VII. Electrical performance limits shall be in accordance with the detail specification.
- 4.2.10.1 Delta limits review. Unless otherwise specified, delta limits shall be in accordance with Table II herein.
- 4.2.10.2 Percent defective allowable (PDA). The percent defective allowable shall be 2 percent or one device, whichever is greater. PDA accountability shall be based on failures occurring during the second half of burn-in only. PDA shall be applicable to the +25 °C static tests only.
- 4.2.11. Seal test. The seal test may be performed in any sequence between the final electrical test and the external visual but it shall be performed after all shearing and forming operations on the terminals. All hybrid crystal oscillators having any physical processing steps (e.g. solder dipping to the glass seal, etc.) performed following seal or external visual shall be retested for hermeticity and visual defects.
- 4.2.12. Radiographic Inspection. Radiographic inspection shall be performed in accordance with MIL-STD-883, method 2012. Views X, Y and Z axis.
- 4.2.13. Frequency aging. The energized oscillator(s) shall be maintained at a temperature of 70 ± 3 °C for a continuous period of 30 days. Unless otherwise specified, the frequency of the oscillator shall be measured in accordance with MIL-PRF-55310. The measuring instrument's accuracy shall be commensurable with the required accuracy of the oscillator. The same measuring instruments shall be used throughout the aging test. If any condition develops that will change the temperature of the oscillator from the aging temperature for a time interval of more than one hour, no measurement shall be made until 24 hours after the temperature restoration and the specified test period shall be lengthened by the length of time that the temperature failed. Tests may be terminated after 15 days if the drifts do not exceed one-half of the delta limits specified in the detail specification.
- 4.2.14. External visual. The final external visual screen shall be conducted in accordance with MIL-STD-883, method 2009 after all other 100 percent screens have been performed to determine that no damage to, or contamination of the package exterior has occurred.



- 4.3 Quality Conformance Inspection (QCI). Quality conformance inspection shall be as specified herein. All records shall be traceable to the lot number and unit serial number. Samples used for Group A that pass all tests may be delivered on contract.
- 4.3.1. Oscillator Group A Inspection. Group A testing shall be in accordance with Table III. Group A inspection shall be performed on units that have passed the screening tests. All electrical performance tests of this specification shall be performed during Group A with the exception of any tests performed as part of final electrical testing during 100 percent screening.
- 4.3.2. Oscillator Group B Inspection. Group B inspection shall be in accordance with Table IV. The screening test rejects may be used for thistest.
- 4.3.3. Oscillator Group C Inspection. Group C inspection shall be in accordance with Table V.
- 4.3.4. Oscillator Group D Inspection. Group D inspection shall be performed per Table VI. The generic package evaluation data may be submitted to Customer for review in lieu of performing this test.
- 4.3.4.1 Group D samples. Sealed empty packages that have been subjected to the handling and stress conditions maybe used for Group D testing.
- 4.4 Destructive Physical Analysis (DPA). A DPA may be performed on each lot of devices in accordance with MIL-STD-883, Method 5009. The DPA shall be performed by the Customer.
- 4.5 Workmanship. Devices shall be manufactured, processed, and tested in a careful and workmanlike manner in accordance with good engineering practice, with the requirements of this specification, and with the production practices, workmanship instructions and inspections and test procedures prepared by the manufacturer in fulfillment of the product assurance program.
- 4.6 Data.
- 4.6.1. Design and Part Configuration Documentation. The manufacturer shall establish baseline documentation sufficient to completely define and control the configuration of devices supplied to this specification. The documentation shall form the basis for defining the device qualified to this specification and all devices supplied on subsequent procurement shall be the same as that qualified. No changes in construction, technology, or manufacturing processing shall occur without Customer approval.
- 4.6.2. Design Documentation. When required by the purchase order, design, topography, schematic circuit, process and flow charts for all assembly/inspection and test operation for devices to be supplied under this specification on the initial procurement shall be established and shall be available in-plant for review by the procuring activity upon request. This design documentation shall be sufficient to depict the physical and electrical construction of the devices supplied under the specification and shall be traceable to the specific parts, drawings or part type numbers to which it applies, and to the production lot(s) and inspection lot codes under which devices are manufactured and tested so that revisions can be identified.
- 4.6.2.1 Technical Data Package. When required by the detail specification or purchase order, the following design documentation and information is deliverable 30 days prior to the start of production. The Technical Data Package shall consist of the following:
- a) Assembly drawing(s).
 - b) All electrical schematics and drawings not considered proprietary.
 - c) The assembly and screening travelers to be used on-line to manufacture the devices supplied to this specification.



d) Parts and materials list.

4.6.3. Design Documentation Approval. After the design documentation referenced in 4.6 is approved by Customer, any changes or revisions to these documents must be submitted for review and approval to Customer prior to processing subsequent lots, or at the time of placement of subsequent purchase order.

4.7 Test Report. A test report shall be supplied with each shipment of oscillators and shall include the following information, as a minimum:

a) A Certificate of Conformance to all specifications and purchase order requirements. As a minimum, the Certificate of Conformance shall include the following information:

- Purchase order number.
- Applicable part number.
- Manufacturers lot number.
- Lot date code.

b) Parts and materials traceability information.

c) Certificate of crystal sweeping.

d) Manufacturing lot traveler.

e) Screening attributes and variables data as applicable.

f) Quality conformance inspection attributes and variables data as applicable.

g) Radiographic inspection negatives.

4.8 Problem Reporting. The manufacturer shall notify the Customer technical representative, within 24 hours, of the occurrence of the following:

a) Any failures detected during quality conformance inspection.

b) Delays resulting from test equipment breakdown, test error, or testing related problems that adversely affect the schedule.

4.9 Customer Source Inspection. Provisions for periodic in-process source inspection by Customer shall be included in the supplier's manufacturing plan. The supplier shall provide Customer 72 hours minimum notice when the deliverable devices are ready for an in-process source inspection. The inspection points shall, as a minimum, be:

a) Pre cap visual inspection.

b) Prior to shipment inspection.

4.10 Retention of Records. All records pertaining to the design, processes, incoming receiving, in-process inspections, screening and quality conformance inspection, product lot identification, product traceability, failure reports and analyses etc., shall be retained by the vendor for a period of 10 years from the date of product shipment.

5 PREPARATION FOR DELIVERY

5.1 Packaging. The requirements for packaging shall be in accordance with MIL-PRF-55310.

5.2 Electrostatic Discharge Sensitivity. The devices supplied to this drawing shall be considered to be



electrostatic discharge sensitive and require further protection and shall use one of the packaging requirements in accordance with MIL-PRF-38534, Category A, Section 5.

6 NOTES

6.1 Ordering Data. The contract or purchase order should specify the following:

- a) Customer part number.
- b) Quality Conformance Inspection requirements.
- c) Requirements for special technical documentation (see 4.6.2.1).
- d) Test data requirements.
- e) Special packaging.
- f) Requirement for source inspection and notification.

6.2 Handling. The devices used must be handled with certain precautions to avoid damage due to electrostatic discharge.

6.3 Certificate of Conformance. Certificate of conformance to this specification, signed by an authorized representative of the manufacturer, shall accompany each shipment.

6.4 Approved Sources of Supply. See detail specification.

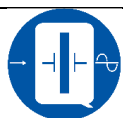


Table I – Screening Tests

| Test Description | Standard | Method | Condition | Comments |
|--|---|--------|---------------------|---------------------------|
| Nondestructive Wire Bond Pull | 883 | 2023 | | 2.4 Grams |
| Internal Visual | 883 | 2017 | K | Class S |
| Stabilization Bake | 883 | 1008 | C | 48 Hours at 150°C |
| Temperature Cycling | 883 | 1010 | C | |
| Constant Acceleration | 883 | 2001 | A | Y ₁ Axis Only |
| Particle Impact Noise Detection (PIND) | 883 | 2020 | B | 5 Passes Minimum (Note 1) |
| Pre Burn-In Electrical | Refer to Table VII and Detail SCD | | | |
| Burn-In | 883 | 1015 | 125°C for 160 Hours | Note 2 |
| Interim Electrical | Refer to Tables II and VII and Detail SCD | | | |
| Burn-In | 883 | 1015 | 125°C for 160 Hours | Note 2 |
| Fine Electrical | Refer to Tables II and VII and Detail SCD | | | |
| Seal; Fine Leak | 883 | 1014 | B1 | |
| Seal; Gross Leak | 883 | 1014 | B2 or B3 | Note 3 |
| Radiographic Inspection | 883 | 2012 | Class S | |
| Frequency Aging | MIL-PRF-55310 | - | 70 ± 3°C | Note 4 |
| External Visual | 883 | 2009 | | |

NOTES

1. PIND testing shall be performed using five (5) independent passes and all failures found at the end of each pass are rejected. The survivors of the last pass are acceptable.
2. Burn-in shall be under the specified load and nominal voltage conditions unless otherwise specified in detail specification.
3. Test condition B2 or B3 shall be selected per internal free cavity volume of package.
4. Normally, frequency aging tests are for 30 days. However, the frequency aging test may be ceased if after 15 days the measured aging rate is less than half of the specified aging rate.
5. Percent defective allowable (PDA) of selected critical parameters is accountable from interim to final electrical testing.

Table II – Delta Limits

| Test | Parameter | Symbol | Delta Limits |
|--|------------------|------------------------|-------------------------|
| Burn-In (Second 160 Hour Burn-In Period) | Supply Current | I _{cc} | ±10% of Initial Reading |
| Frequency Aging After 30 Days at 70°C | Output Frequency | F ₀ | Refer to Detail SCD |
| Life Test After 1000 Hours at 125°C | Supply Current | I _{cc} (Life) | ±10% of Initial Reading |

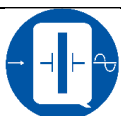


Table III – Group A Inspection (NOTE 1)

| Test Description | Condition |
|---|--|
| Supply Current | 25°C and Temperature Extremes |
| Initial Accuracy at Reference Temperature | 25°C |
| Frequency-Temperature Stability | Over Specified Operating Temperature Range, Measure Output Frequency at Minimum Ten Equally Spaced Points of the Temperature Extremes 25°C and Temperature Extremes |
| Frequency-Voltage Tolerance | |
| Output Voltage | |
| Duty Cycle (Output Waveform Symmetry) | |
| Output Rise and Fall Times | |
| Start Up Time | |
| Jitter 2/ | |
| Phase Noise 2/ | |
| Spurious 2/ | |
| Enable/Disable 2/ | |

NOTES

1. All electrical performance shall be performed during Group A with the exception of any tests performed as part of final electrical testing during 100 percent screening.
2. Only if parameter is specified in detail specification.

Table IV – Group B Inspection (NOTE 1)

| Sub Group | Test Description | MIL-STD-883 | | Quantity (Accept No.) |
|-----------|---|-------------|----------------------------------|-----------------------|
| | | Method | Condition | |
| 1 | Physical Dimensions | 2016 | - | 2 (0) |
| 2 | Particle Impact Noise Detection (PIND) (Note 2) | 2020 | B | 15 (0) |
| 3 | Resistance to Solvents | 2015 | - | 3 (0) |
| 4 | Internal Visual and Mechanical | 2014 | - | 1 (0) |
| 5 | Bond Strength (Note 3) | 2011 | C or D | 2 (0) |
| 6 | Die Shear Strength (Note 4) | 2019 | - | 2 (0) |
| 7 | Solderability (Note 5) | 2003 | Solder Temperature: 245 ± 5°C | 1 (0) |
| 8 | Seal; Fine and Gross Leak (Note 6) | 1014 | B1 and B2/B3 | 4 (0) |
| 9 | ESD Classification (Note 7) | 3015 | - | 3 (0) + 3 |

NOTES

1. Non catastrophic screening test rejects may be used for Group B.
2. To be omitted. Being performed during screening, see Table 1.
3. Subgroup 5 shall be performed in accordance with the Group B bond strength requirements of MIL-PRF-38534. This test may be performed in-process any time prior to cover seal.
4. Die shear test samples shall not be the same units as subjected to bond pull. Die shear specimens shall not be exposed to the 300 °C preconditioning used for the bond strength test.
5. Solder temperature shall be 245 +5 °C.
6. Subgroup 8, the fine and gross leak tests are being done during screening, see Table III.
7. Subgroup 9, the ESD classification test, is not required. The hybrid has been classified as ESDS Class 1C (Electrostatic voltage = 1,000V to 1,999 V) and shall be marked accordingly. Total of six units required (three units for testing and three units for setup).

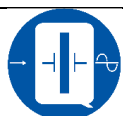


Table V – Group C Inspection

| Sub Group | Test Description | MIL-STD-883 | | Quantity (Accept No.) |
|-----------|------------------------------|-------------|------------------------|-----------------------|
| | | Method | Condition | |
| 1 | External Visual | 2009 | C | 5 (0) |
| | Temperature Cycling | 1010 | 20 Cycles | |
| | Constant Acceleration | 2001 | A, Y ₁ Axis | |
| | Seal; Fine Leak | 1014 | B1 | |
| | Seal; Gross Leak | 1014 | B2 or B3 | |
| | Radiographic Inspection | 2012 | | |
| | Visual Examination | | | |
| | End Point Electricals | | | |
| 2 | End Point Electricals | 1005 | 1000 Hours at 125°C | 5 (0) |
| | Steady State Life | | | |
| | End Point Electricals | | | |
| 3 | Internal Water Vapor Content | 1018 | | 3 (0) or 5 (1) |

NOTES

1. It is recommended to use 10 specimens for Group C Inspection - 5 units for Subgroups 1 and 3 and 5 units for Subgroup 2. 5 units may be used for Group C Inspection but the Customer procures this quantity at their own risk. Usage of specimens that have completed Subgroups 1 and 2 Testing for Subgroup 3 Testing is not recommended. This limited acquisition shall only be used if this risk is acceptable to the Customer, and the Customer assumes responsibility for Subgroup 3 failures if only five units are procured for Group C Inspection.
2. Subgroup 1 specimens shall be used for subgroup 3 testing.
3. End point electrical shall be as specified in the detail SCD.

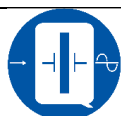


Table VI – Group D Inspection

| Sub Group | Test Description | MIL-STD-883 | | Quantity (Accept No.) |
|-----------|---------------------------|-------------|-------------------------------------|-----------------------|
| | | Method | Condition | |
| 1 | Thermal Shock | 1011 | C | 5 (0) |
| | Stabilization Bake | 1008 | 1 Hour at 150°C | 5 (0) |
| | Lead Integrity | 2004 | B2 (Lead Fatigue) | 1 (0) |
| | Seal; Fine and Gross Leak | 2028 | D (LCC) Rigid Leads B1 and B2/B3 | 5 (0) |

Table VII – Electrical Test, Measurement Requirements

| Electrical Parameters | Test Step and Environmental Condition | | | | | | | | | | |
|---------------------------------|---------------------------------------|-------------------------|--------------------------|------------------------|---------------------|--------------------------|---------------------------|----------------|---------------------|----------------------|---------|
| | Pre Burn-In @ 25°C | Pre Burn-In @ Low Temp. | Pre Burn-In @ High Temp. | Interim Burn-In @ 25°C | Post Burn-In @ 25°C | Post Burn-In @ Low Temp. | Post Burn-In @ High Temp. | Group A @ 25°C | Group A @ Low Temp. | Group A @ High Temp. | Group C |
| Output Frequency | X | X | X | X | X | X | X | X | X | X | 3/ |
| Frequency-Temperature Stability | | | | | | | | See Note 1 | | | |
| Frequency-Voltage Tolerance | X | | | | X | | | X | X | X | X |
| Input Current | X | | | X | X | X | X | X | X | X | X |
| Output Voltage | X | X | X | X | X | X | X | X | X | X | X |
| Waveform | X | X | X | X | X | X | X | X | X | X | X |
| Duty Cycle (Symmetry) | X | X | X | X | X | X | X | X | X | X | X |
| Rise and Fall Times | X | | | X | X | X | X | X | X | X | X |
| Start Up Time | X | | | X | X | | | X | X | X | X |
| Jitter 4/ | X | | | | X | | | X | X | X | X |
| Phase Noise 4/ | X | | | | X | | | X | X | X | X |
| Spurious 4/ | X | | | | X | | | X | X | X | X |
| Enable/Disable 4/ | X | | | | X | | | X | X | X | X |

X = Required Measurement

NOTES

1. Measure the output frequency at ten equally spaced points minimum of the specified operating temperature range.
2. Temperature extremes shall be as specified in the detail SCD.
3. Frequency accuracy (and/or frequency-temperature stability) limits for post steady state life electrical testing shall be relaxed by six times the projected first year aging limit as specified in the detail specification. If no such limit is specified, the limit shall be relaxed ±60ppm. Notwithstanding, device performance that appears out-of-family shall be subjected to further evaluation.
4. Only if parameter is specified in detail specification.

